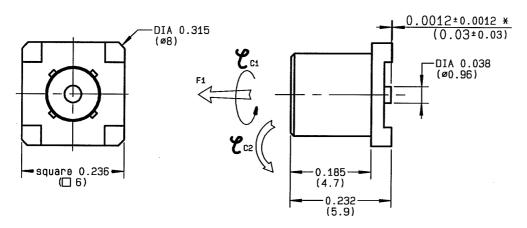
R113.424.000

Series : MCX

*set back of c. contact from body (Retrait du c. central/ au corps)



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	BRASS BERYLLIUM COPPER - PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2	

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PACKAGING

Standard Unit Other 100 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω Frequency 0-6 GHz

Frequency **0-6** GHz VSWR **1.05** + **0.050** x F(GHz) Maxi

Insertion loss 0.03 VF(GHz) Maxi

RF leakage - (NA - F(GHz)) dB Maxi Voltage rating 335 Veff Maxi Dielectric withstanding voltage 1000 Veff mini

Dielectric withstanding voltage 1000 Veff mini Insulation resistance 1000 M Ω mini

ENVIRONMENTAL

Operating temperature -55/+155 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

FORCE F1:90N-TORQUES C1:45Ncm-C2:80Ncm

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

10 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.620** g

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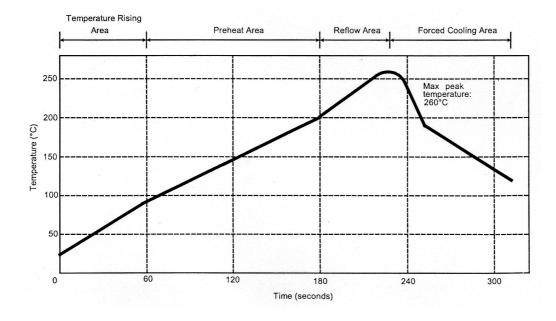
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SOLDER PROCEDURE

- Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application.
 We recommend a low residue flux. We advise a thickness of 150 microms mini. (.006 inch mini).
 Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 Aspiration port (see page 4) centered into body and push against it.
 A video camera is recommended for positioning of the component.
 Adhesive agents must not be used on the receptacle.
- Soldering by infra-red reflow.
 Below please find ,the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



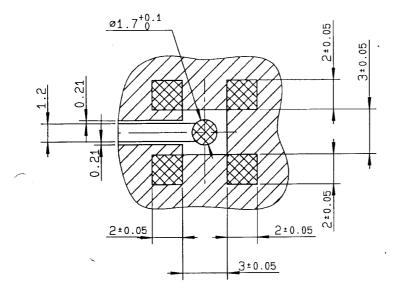
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

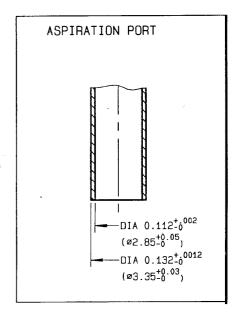
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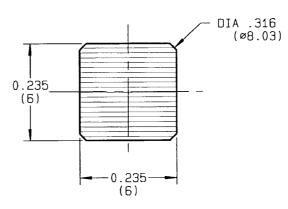


COPLANAR LINE
Pattern and signal are on the same side
Thickness of PCB: .063 (1.6 mm)
The material of PCB is the epoxy resin
of glass fabrics bacs.(Er = 4.8)
The solder resist should be printed
exept for the land pattern on the PCB.

Pattern

Land for solder paste

SHADOW OF MCX RECEPTACLE FOR VIDEO CAMERA



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